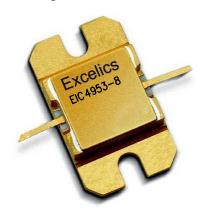


ISSUED 02/28/2008

# 4.90-5.30 GHz 8-Watt Internally Matched Power FET

#### **FEATURES**

- 4.90-5.30GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.5 dBm Output Power at 1dB Compression
- 10.5 dB Power Gain at 1dB Compression
- 35% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- 100% Tested for DC, RF, and R<sub>TH</sub>





# **ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25°C)**

Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS <sup>1</sup>		TYP	MAX	UNITS
P <sub>1dB</sub>	Output Power at 1dB Compression $f = 4.90-5.30GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	38.5	39.5		dBm
G <sub>1dB</sub>	Gain at 1dB Compression $f = 4.90-5.30GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	9.5	10.5		dB
ΔG	Gain Flatness $f = 4.90-5.30 GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200 \text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS}$ = 10 V, $I_{DSQ} \approx 2200$ mA f = 4.90-5.30GHz		35		%
Id <sub>1dB</sub>	Drain Current at 1dB Compression f = 4.90-5.30GHz		2300	2600	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f$ =10MHz 2-Tone Test. Pout=28.5 dBm S.C.L Vds = 10 V, I <sub>DSQ</sub> ≈ 65% I <sub>DSS</sub> f = 5.30GHz	-43	-46		dBc
I <sub>DSS</sub>	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		4000	5000	mA
$V_P$	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 40 \text{ mA}$		-2.5	-4.0	V
R <sub>TH</sub>	Thermal Resistance <sup>3</sup>		3.5	4.0	°C/W

## Note: 1. Tested with 100 Ohm gate resistor. 2. S.C.L. = Single Carrier Level.

## **ABSOLUTE MAXIMUM RATING**<sup>1,2</sup>

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>	
Vds	Drain-Source Voltage	15	10V	
Vgs	Gate-Source Voltage	-5	-4.5V	
lgsf	Forward Gate Current	86.4mA	28.8mA	
lgsr	Reverse Gate Current	-14.4mA	-4.8mA	
Pin	Input Power	38.5dBm	@ 3dB Compression	
Tch	Channel Temperature	175°C	175 °C	
Tstg	Storage Temperature	-65 to +175 °C	-65 to +175 °C	
Pt	Total Power Dissipation	38W	38W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

<sup>3.</sup> Overall Rth depends on case mounting.

<sup>2.</sup> Exceeding any of the above ratings may reduce MTTF below design goals.



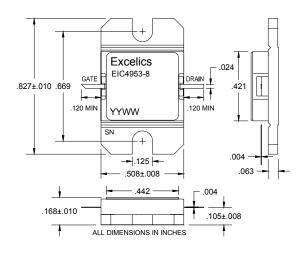
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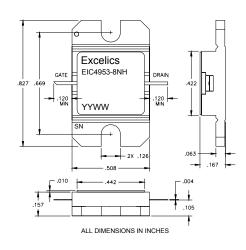
#### PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

### EIC4953-8 (Hermetic)









Caution! ESD sensitive device.



Caution! ESD sensitive device.

## **ORDERING INFORMATION**

Part Number	Packages	Grade <sup>1</sup>	f <sub>Test</sub> (GHz)	P <sub>1dB</sub> (min)	IM <sub>3</sub> (min) <sup>2</sup>
EIC4953-8	Hermetic	Industrial	4.90-5.30GHz	38.5	-43
EIC4953-8NH	Non-Hermetic	Industrial	4.90-5.30GHz	38.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness